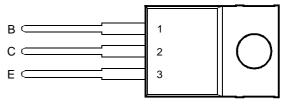
- Designed for Complementary Use with the TIP31 Series
- 40 W at 25°C Case Temperature
- 3 A Continuous Collector Current
- 5 A Peak Collector Current
- Customer-Specified Selections Available

### TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRACA

### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT
	TIP32		-80	
Collector-base voltage (I <sub>F</sub> = 0)	TIP32A	\/	-100	V
Collector-base voltage (IE = 0)	TIP32B	V <sub>CBO</sub>	-120	٧
	TIP32C		-140	
	TIP32		-40	
Collector-emitter voltage (I <sub>B</sub> = 0)	TIP32A	\/	-60	V
	TIP32B	V <sub>CEO</sub>	-80	
	TIP32C		-100	
Emitter-base voltage			-5	V
Continuous collector current			-3	Α
Peak collector current (see Note 1)			-5	Α
Continuous base current			-1	Α
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			40	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			2	W
Unclamped inductive load energy (see Note 4)			32	mJ
Operating junction temperature range			-65 to +150	°C
Storage temperature range			-65 to +150	°C
Lead temperature 3.2 mm from case for 10 seconds			250	°C

NOTES: 1. This value applies for  $t_p \le 0.3$  ms, duty cycle  $\le 10\%$ .

- 2. Derate linearly to 150°C case temperature at the rate of 0.32 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
- 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH,  $I_{B(on)}$  = -0.4 A,  $R_{BE}$  = 100  $\Omega$ ,  $V_{BE(off)}$  = 0,  $R_S$  = 0.1  $\Omega$ ,  $V_{CC}$  = -20 V.



# TIP32, TIP32A, TIP32B, TIP32C PNP SILICON POWER TRANSISTORS

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# electrical characteristics at 25°C case temperature

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT	
.,	Collector-emitter  O breakdown voltage			TIP32 TIP32A	-40 -60			.,	
V <sub>(BR)CEO</sub>		breakdown voltage	I <sub>C</sub> = -30 mA (see Note 5)	I <sub>B</sub> = 0	TIP32B	-80			V
		,		TIP32C	-100				
		V <sub>CE</sub> = -80 V	$V_{BE} = 0$	TIP32			-0.2		
loso	Collector-emitter	V <sub>CE</sub> = -100 V	$V_{BE} = 0$	TIP32A			-0.2	mA	
I <sub>CES</sub>	cut-off current	V <sub>CE</sub> = -120 V	$V_{BE} = 0$	TIP32B			-0.2	1117 (	
		V <sub>CE</sub> = -140 V	$V_{BE} = 0$	TIP32C			-0.2		
I <sub>CEO</sub>	Collector cut-off	V <sub>CE</sub> = -30 V	I <sub>B</sub> = 0	TIP32/32A			-0.3	mA	
ICEO	current	V <sub>CE</sub> = -60 V	$I_B = 0$	TIP32B/32C			-0.3	ША	
I <sub>EBO</sub>	Emitter cut-off	V <sub>EB</sub> = -5 V	I <sub>C</sub> = 0				-1	mA	
·EBO	current								
h <sub>FE</sub>	Forward current	V <sub>CE</sub> = -4 V	$I_C = -1 A$	(see Notes 5 and 6)	25				
	transfer ratio	V <sub>CE</sub> = -4 V	$I_C = -3 A$		10		50		
V <sub>CE(sat)</sub>	Collector-emitter	I <sub>B</sub> = -375 mA	I <sub>C</sub> = -3 A	(see Notes 5 and 6)			-1.2	V	
*CE(Sat)	saturation voltage								
$V_{BE}$	Base-emitter	V <sub>CE</sub> = -4 V	$_{CE} = -4 \text{ V}$ $I_{C} = -3 \text{ A}$	(see Notes 5 and 6)			-1.8	V	
, DE	voltage								
h <sub>fe</sub>	Small signal forward	Vor = -10 V	$V_{CE} = -10 \text{ V}$ $I_{C} = -0.5 \text{ A}$	$I_0 = -0.5 A$	f = 1 kHz	20			
··ie	current transfer ratio	- CE							
h <sub>fe</sub>	Small signal forward current transfer ratio	V <sub>CE</sub> = -10 V	$I_C = -0.5 A$	f = 1 MHz	3				
	current transier ratio	1			l				

NOTES: 5. These parameters must be measured using pulse techniques,  $t_p$  = 300  $\mu$ s, duty cycle  $\leq$  2%.

### thermal characteristics

	PARAMETER			MAX	UNIT
$R_{\theta J}$	Junction to case thermal resistance			3.125	°C/W
$R_{\theta J}$	Junction to free air thermal resistance			62.5	°C/W

## resistive-load-switching characteristics at 25°C case temperature

Ī		PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
Ī	t <sub>on</sub>	Turn-on time	I <sub>C</sub> = -1 A	$I_{B(on)} = -0.1 \text{ A}$	$I_{B(off)} = 0.1 A$		0.3		μs
Ī	t <sub>off</sub>	Turn-off time	$V_{BE(off)} = 4.3 \text{ V}$	$R_L = 30 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		1		μs

 $<sup>^{\</sup>dagger} \ \ \mbox{Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.}$ 

<sup>6.</sup> These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

### TYPICAL CHARACTERISTICS

# TYPICAL DC CURRENT GAIN VS COLLECTOR CURRENT $T_{CS632AA}$ $T_{C} = 25^{\circ}C$ $T_{C}$

Figure 1.

**COLLECTOR-EMITTER SATURATION VOLTAGE** 

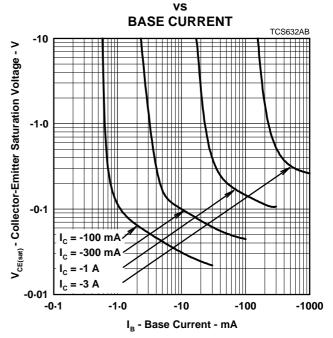


Figure 2.

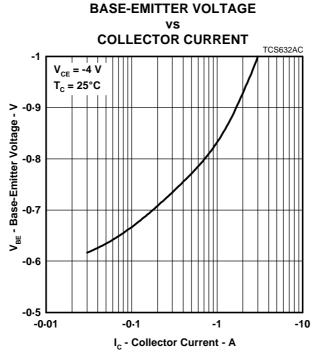
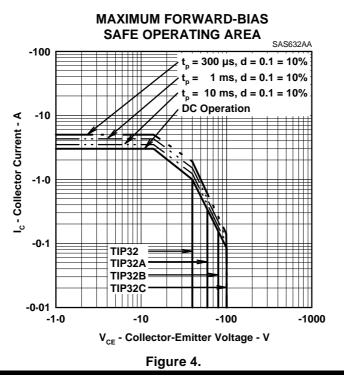


Figure 3.

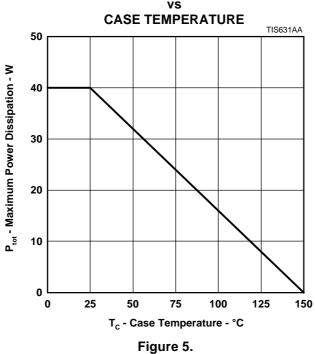


### **MAXIMUM SAFE OPERATING REGIONS**



### THERMAL INFORMATION

# MAXIMUM POWER DISSIPATION

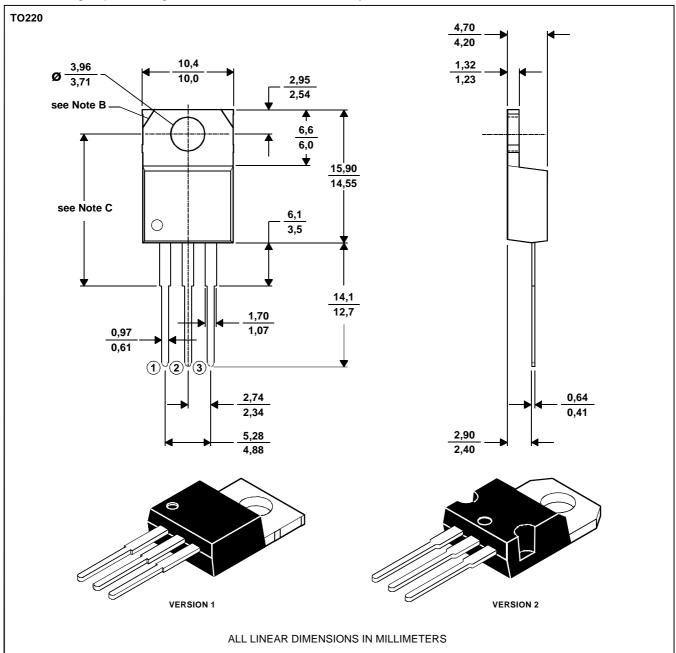


### **MECHANICAL DATA**

### **TO-220**

### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.
 Typical fixing hole centre stand off height according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. MDXXBE



# TIP32, TIP32A, TIP32B, TIP32C PNP SILICON POWER TRANSISTORS

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